

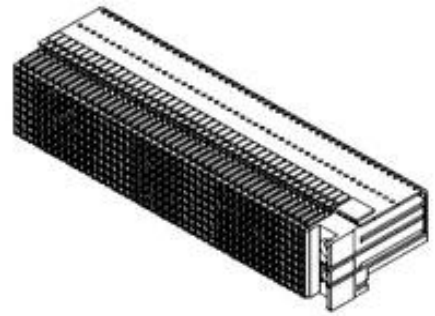
Part Number : [740401343](#)

Product Description : VHDM Daughtercard,
2.00mm Pitch, 8-Rows, 25 Wafers, 200 Circuits, Tin
Lead, Guide Module

Series Number : 74040

Status : Active

Product Category : Backplane Connectors



Documents and Resources

Drawings

[PK-70873-5041-001.pdf](#)

Specifications

[PS-74031-999-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)7771-DC (04 Feb 2026)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

Part Details

General

Status	Active
Category	Backplane Connectors
Series	74040
Description	VHDM Daughtercard, 2.00mm Pitch, 8-Rows, 25 Wafers, 200 Circuits, Tin Lead, Guide Module
Application	Backplane
Comments	Daughter Card
Component Type	PCB Header
Product Name	VHDM
UPC	883906551841

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Data Rate	3.125 Gbps
Shielded	Yes
Voltage - Maximum	120V AC (RMS)/DC

Physical

Circuits (Loaded)	200
Circuits (maximum)	200
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes

Keying to Mating Part	N/A
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Matte Tin
Material - Resin	High Performance Thermoplastic
Net Weight	59.065/g
Number of Columns	25
Number of Pairs	N/A
Number of Rows	8
Orientation	Right Angle
Packaging Type	Tube
PCB Locator	No
PCB Retention	No
PCB Thickness - Recommended	1.80mm
PC Tail Length	2.80mm
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Polarized to PCB	No
Stackable	Yes
Temperature Range - Operating	-55° to +80°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A
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Application Tooling

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